

Description

The HXY2302AI uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

V_{DS} = 20V I_D = 3.0A

 $R_{DS(ON)} < 45 m\Omega @ V_{GS}=4.5V$

Application

Battery protection

Load switch Uninterruptible power supply

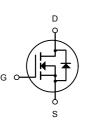
Package Marking and Ordering Information

| Product ID | Pack | Marking | Qty(PCS) |
|------------|--------|----------------|----------|
| HXY2302AI | SOT-23 | A2SHB XXX YYYY | 3000 |

Absolute Maximum Ratings (T_A=25[°]C unless otherwise noted)

| Symbol | Parameter | Limit | Unit |
|------------------|--|------------|------|
| Vds | Drain-Source Voltage | 20 | V |
| V _G s | Gate-Source Voltage | ±12 | V |
| ID | Drain Current-Continuous | 3 | A |
| Ідм | Drain Current-Pulsed (Note 1) | 16 | А |
| P _D | Maximum Power Dissipation | 0.9 | W |
| TJ,TSTG | Operating Junction and Storage Temperature Range | -55 To 150 | °C |
| Reja | Thermal Resistance, Junction-to-Ambient (Note 2) | 139 | °C/W |





N-Channel MOSFET



| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|----------------------------------|-------------------|---|-----|------|------|------|
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =250µA | 20 | 22 | - | V |
| Zero Gate Voltage Drain Current | IDSS | V _{DS} =20V,V _{GS} =0V | - | - | 1 | μA |
| Gate-Body Leakage Current | lgss | V _{GS} =±12V,V _{DS} =0V | - | - | ±100 | nA |
| Gate Threshold Voltage | VGS(th) | V _{DS} =V _{GS} ,I _D =250µA | 0.5 | 0.75 | 1.2 | V |
| | Rds(on) | V _{GS} =2.5V, I _D =2.8A | - | 35 | 60 | mΩ |
| Drain-Source On-State Resistance | | V _{GS} =4.5V, I _D =3A | - | 29 | 45 | mΩ |
| Forward Transconductance | g fs | V _{DS} =5V,I _D =3A | - | 8 | - | S |
| Input Capacitance | C _{lss} | | - | 260 | - | PF |
| Output Capacitance | Coss | V _{DS} =10V,V _{GS} =0V, | - | 48 | - | PF |
| Reverse Transfer Capacitance | C _{rss} | F=1.0MHz | - | 27 | - | PF |
| Turn-on Delay Time | td(on) | | - | 2.5 | - | nS |
| Turn-on Rise Time | tr | V _{DD} =10V, R∟=3.3Ω | - | 3.2 | - | nS |
| Turn-Off Delay Time | td(off) | V_{GS} =4.5V, R_{GEN} =6 Ω | - | 21 | - | nS |
| Turn-Off Fall Time | t _f | | - | 3 | - | nS |
| Total Gate Charge | Qg | | - | 2.9 | 5 | nC |
| Gate-Source Charge | Q _{gs} | V _{DS} =10V,I _D =3A, | - | 0.4 | - | nC |
| Gate-Drain Charge | Q _{gd} | V _{GS} =4.5V | - | 0.6 | - | nC |
| Diode Forward Voltage (Note 3) | Vsd | V _{GS} =0V,I _S =3.3A | - | 0.75 | 1.2 | V |
| Diode Forward Current (Note 2) | ls | | - | - | 3.3 | Α |

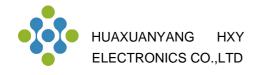
Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. Surface Mounted on FR4 Board, $t \le 10$ sec.

3. Pulse Test: Pulse Width \leq 300µs, Duty Cycle \leq 2%.

4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

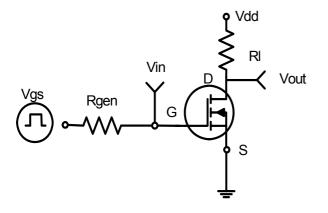


Figure 1:Switching Test Circuit

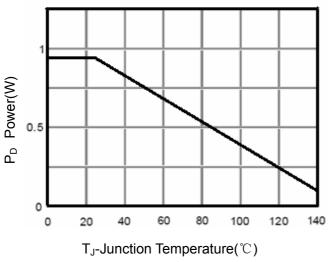
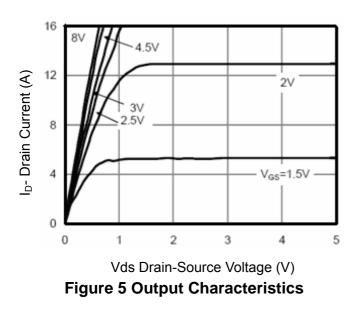
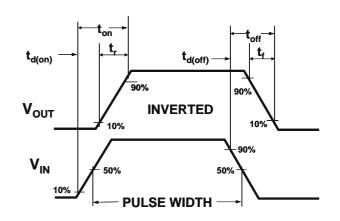


Figure 3 Power Dissipation







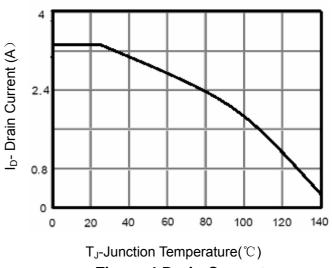


Figure 4 Drain Current

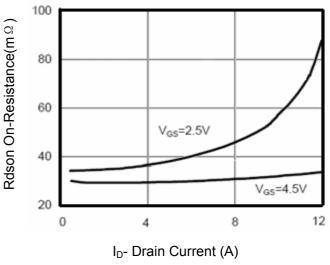
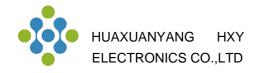
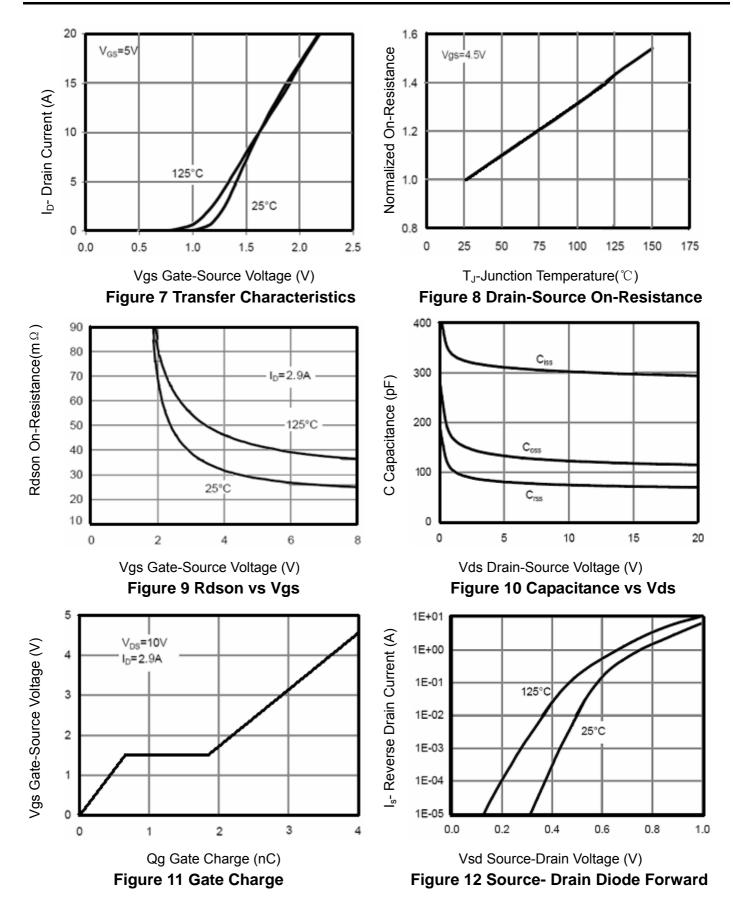


Figure 6 Drain-Source On-Resistance

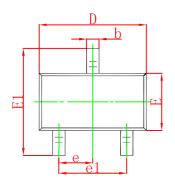


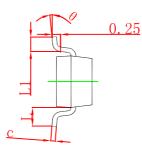
HXY2302AI N-Channel Enhancement Mode MOSFET

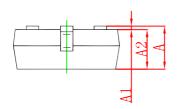




SOT-23 Package Outline Dimensions

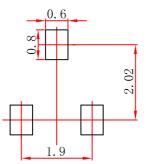






| Symbol | Dimensions In Millimeters | | Dimensions In Inches | | |
|--------|---------------------------|-------|----------------------|-------|--|
| | Min | Max | Min | Max | |
| Α | 0.900 | 1.150 | 0.035 | 0.045 | |
| A1 | 0.000 | 0.100 | 0.000 | 0.004 | |
| A2 | 0.900 | 1.050 | 0.035 | 0.041 | |
| b | 0.300 | 0.500 | 0.012 | 0.020 | |
| С | 0.080 | 0.150 | 0.003 | 0.006 | |
| D | 2.800 | 3.000 | 0.110 | 0.118 | |
| Е | 1.200 | 1.400 | 0.047 | 0.055 | |
| E1 | 2.250 | 2.550 | 0.089 | 0.100 | |
| e | 0.950 TYP | | 0.037 TYP | | |
| e1 | 1.800 | 2.000 | 0.071 | 0.079 | |
| L | 0.550 REF | | 0.022 REF | | |
| L1 | 0.300 | 0.500 | 0.012 | 0.020 | |
| θ | 0° | 8° | 0° | 8° | |

SOT-23 Suggested Pad Layout



Note: 1.Controlling dimension:in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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